Solder paste NP303-WS7157-T7

GENMA EUROPE

Product description

GENMA solder paste – our NP303-WS7157-T7 solder paste with easy to clean water soluble flux. It convinces with its outstanding printability, highly precise contours and consistent adhesiveness in the pick-and-place process. Its extremely good wetting properties, produce perfect soldering joints. Hardly any voids in the solder connections. Cleaning of flux residues with water after soldering is required. The solder paste can be soldered under nitrogen reflow.

Technical properties

	Specific value	Testing method
Alloy	Sn 96,5 / Ag 3,0 / Cu 0,5 / SAC305	
Melting temperature range	217 - 221	IEC61189-11
Powder size (µm)	2 - 11, type 7	IPC-TM-650-2.2.14.2

Compliance

Conform with RoHS-Regulation 2011/65/EU

Contains no substances more than threshold (0,1%) according to REACH legislation EG Nr. 1907/2006 (SVHC-list - dated 27.06.2018)

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